

Reworktool

Additional reworktool to unsolder SMT-components in DF-A vapour phase soldering system

- Easy to use , gentle process and low stress for components during rework process
- High temperature adhesive tape is used to fix the component to the stamp of the reworktool
- Condensing vapour is transferring the heat to the solder joints and the reworktool lifts up the component as soon as the solder paste is melted



To rework BGAs, QFNs, QFPs or other SMT-components



- Re-solder the component in the JS460
 - Soldering temperature 160-240°C

